



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: ) LEAD FRAME FOR A SEMICONDUCTOR  
SHOSHI YASUNAGA et al ) DEVICE, A SEMICONDUCTOR DEVICE  
Serial No. 10/024,827 ) MADE USING THE LEAD FRAME  
Filed December 17, 2001 ) AND A METHOD OF MAKING A  
SEMICONDUCTOR DEVICE  
Group Art Unit 2827  
Examiner Luan C. Thai

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**RESPONSE**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Responsive to the Office Action dated December 3, 2002, Applicant elects to prosecute claims directed to the embodiment (2) in Figures 12-15. Claims 1-7, 9, 10, 14-16, 20-26, 28, 29, 33-35, 39 and 40 are readable on this embodiment. Claims 11-13, 17-19, 30-32 and 36-38 claim a base rail and an interrelationship of parts therewith. While the base rail is not shown in Figures 12-15, it is explained on page 20 of Applicants' specification, in the last

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CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on January 23, 2003

Signature: Karen Sanderson  
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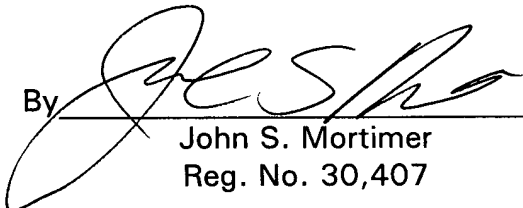
three lines thereof, that the unit lead frames 62' shown in Figs. 12-15 are connected to a base rail, such as the base rail 72, described with respect to other figures. Accordingly, since the description with respect to Figs. 12-15 incorporates the structure shown in other figures, claims 11-13, 17-19, 30-32 and 36-38 likewise read on the embodiment (2) and should be examined with the above-enumerated claims.

An early and favorable action on the merits is requested.

Respectfully submitted,

WOOD, PHILLIPS, KATZ,  
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By



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